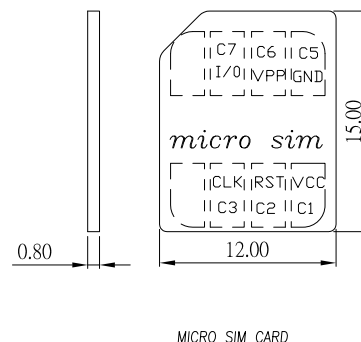
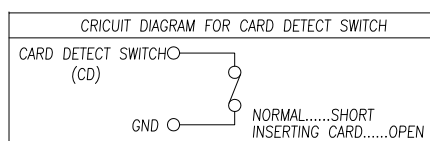
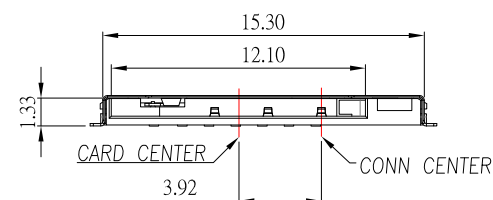
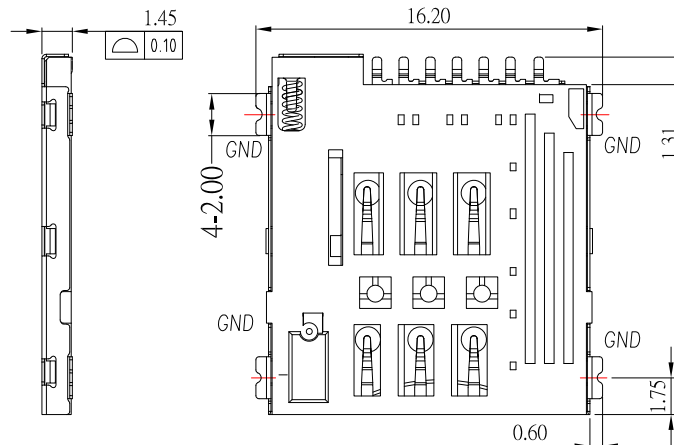
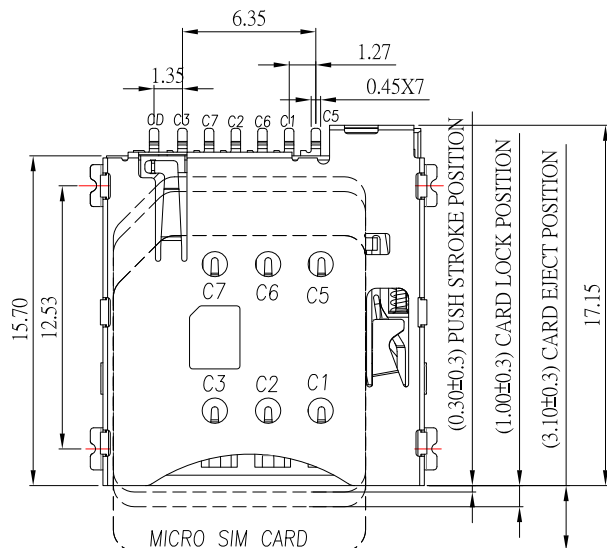
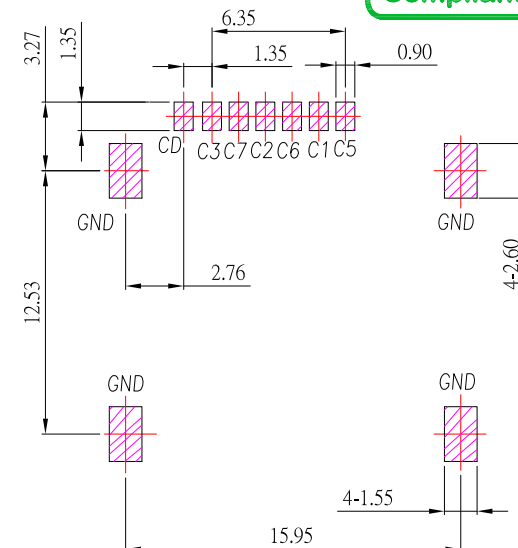




SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



PCB LAYOYT

Material:

- 1.Housing: LCP
- 2.Contact: Copper Alloy
- 3.Shell: SUS

Finish:

- 1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface laye

				建倚科技股份有限公司				DRAWN BY:	DATE	MATL	TITLE	CONNECTOR
				CONTACT TECHNOLOGY CORP.				Jack Lu	10/28/20		MODLE	MICRO SIM CARD PUSH PUSH 7PIN
								CHECKED BY:	DATE	FINISH		1.45H 带CD PIN(防呆型)
								Jacky Chen	10/28/20	SCALE	1 : 1	DWG NO. MSIM-S3071-A1-S304
								APPROVED BY:	DATE	SHEET NO.	1 of 1	PART NO. MSIM-S3071-A1-S304
								Tony Kao	10/28/20			SIZE A4
												VER R3

3	更新樣式	Jack	102820	TOLERANCE UNLESS OTHERWISE STATED :	Up to 5	±0.2	3RD. ANGEL'S	UNITS	MM
2	更新尺寸	Jack	101518		Above 5 ~ 15	±0.3			
1	更新樣式	Jack	101218		Above 15 ~ 30	±0.4			
ITEM NO.	DESCRIPTION	DRAWN	DATE		Above 30 ~ 50	±0.5			
					Angle	±0.3°			